

## Electronic Patent Application Fee Transmittal

**Application Number:**

10576639

**Filing Date:**

**Title of Invention:**

Method for Gluing a Circuit Component to a Circuit Substrate

**First Named Inventor/Applicant Name:**

Willbald Konrath

**Filer:**

Stephen A. Herrera/Laura Wade

**Attorney Docket Number:**

5577-006

Filed as Large Entity

### U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
-------------	----------	----------	--------	----------------------

**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

Late filing fee for oath or declaration	1051	1	130	130
---	------	---	-----	-----

**Petition:**

**Patent-Appeals-and-Interference:**

Post-Allowance and Post-Issue  
12/26/2006 INTEFSW 00001794 10576639  
01 FC:1051 -130.00 OP

04/02/2007 PBOOKER 00000002 10576639

01 FC:1617

130.00 OP

**Extension-of-Time:**